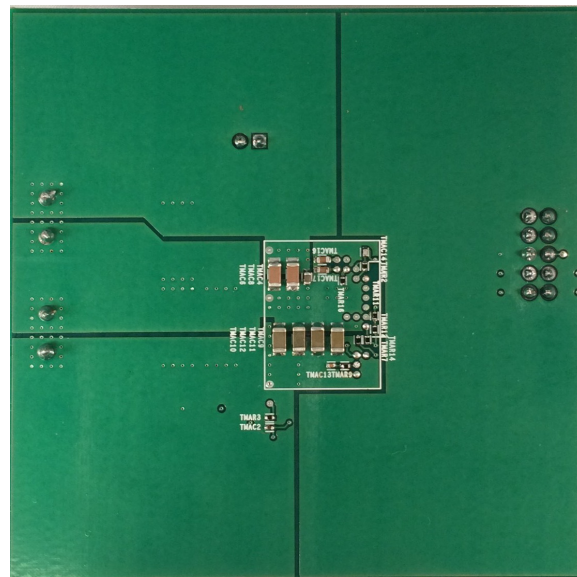
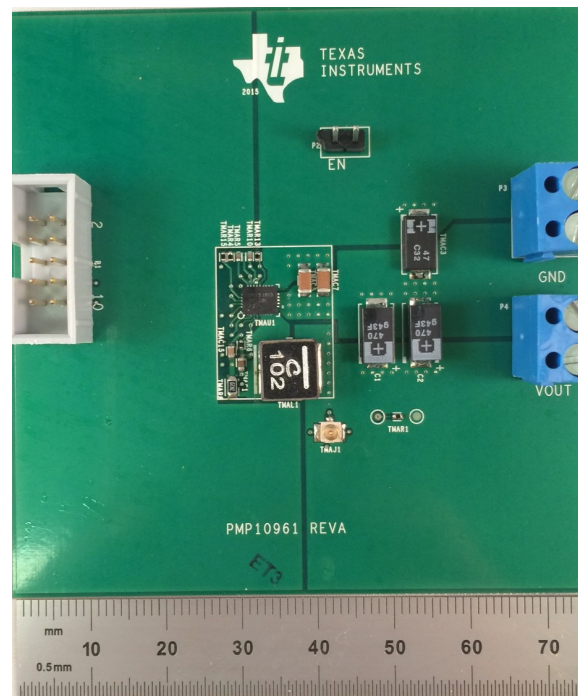
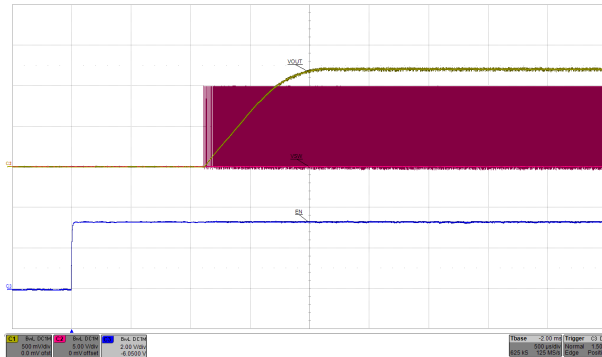


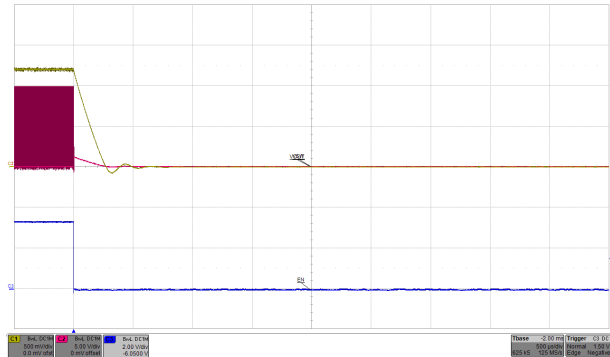
Photo of the prototype



1 Startup and shutdown

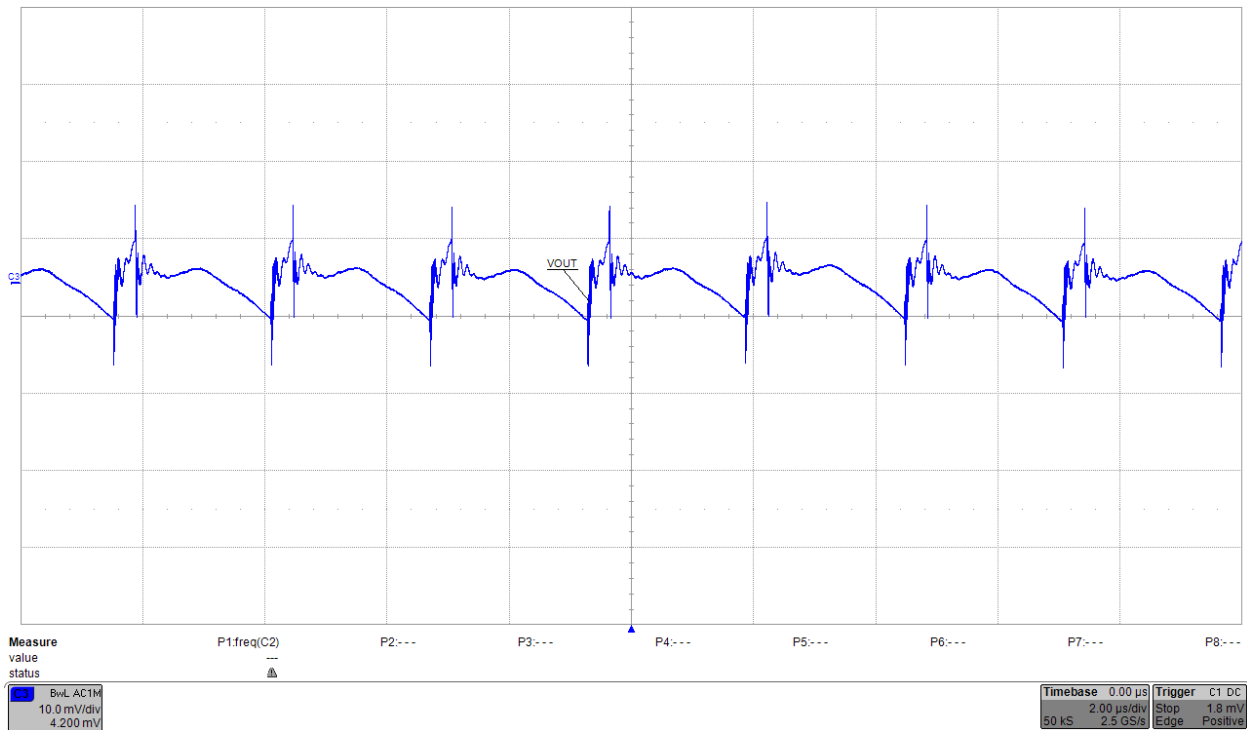


Turn-on, 10Vin, 1.2Vout



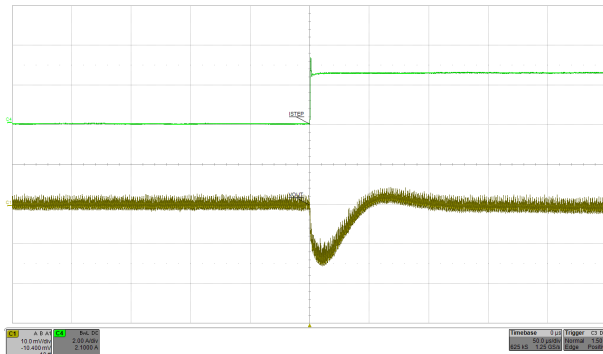
Turn-off, 10Vin, 1.2Vout

2 Ripple

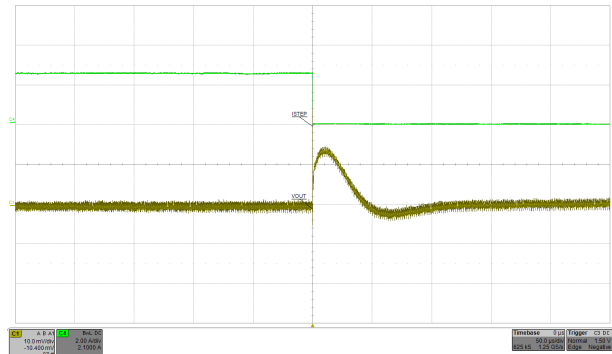


10Vin, 1.2Vout, 10A Load

3 Transient

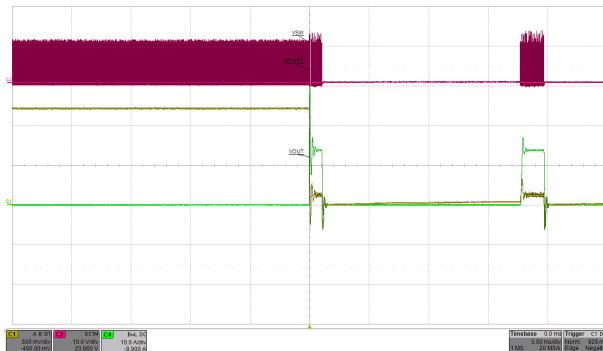


10Vin, 1.2Vout, 7.5A to 10A Load Step

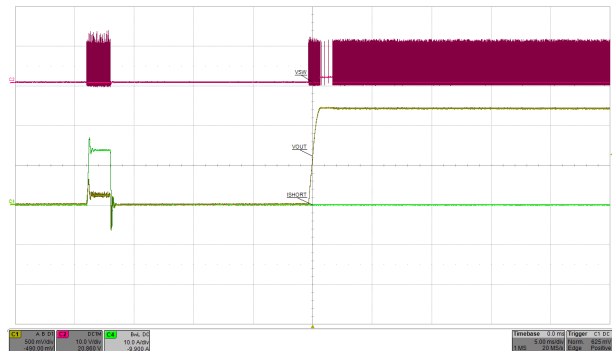


10Vin, 1.2Vout, 10A to 7.5A Load Step

4 Short-circuit protection

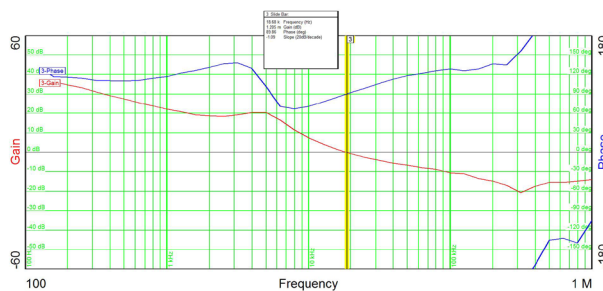


10Vin, 1.2Vout, Short circuit applied

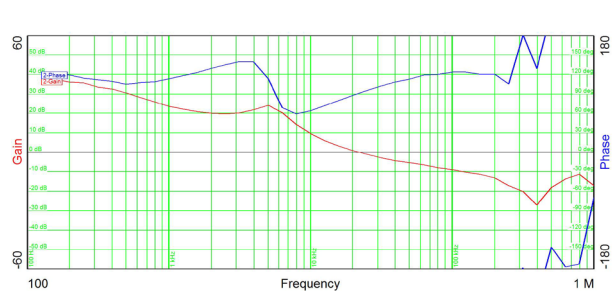


10Vin, 1.2Vout, Short circuit released

5 Bode Plot

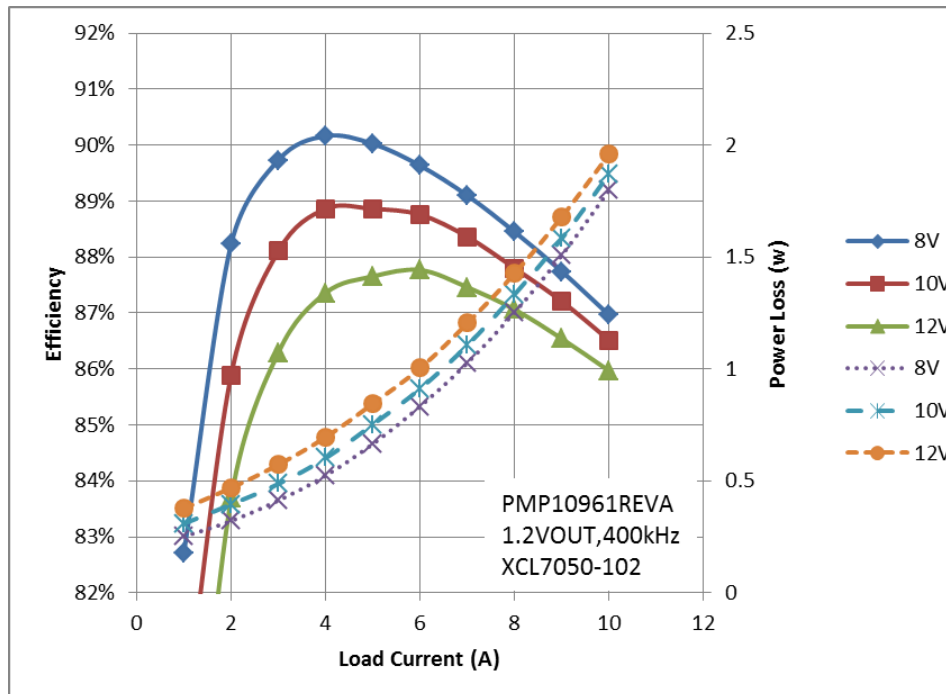


10Vin, 1.2Vout, No Load, BW=18.7kHz, PM=89deg



10Vin, 1.2Vout, 10A Load, BW=22.2kHz, PM=91deg

6 Efficiency



Test conditions: 1.2Vout, 400kHz, XCL7050-102.

7 Thermal



Test conditions: 10Vin, 1.2V/10A, 400kHz, natural convection, room temperature, $T_{IND} = 47.8^\circ\text{C}$, $T_{FET} = 51.3^\circ\text{C}$.

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